

Ball-Wedge Bonder 5610i

Bond System

Wire types	Gold wire 12,5-50 µm on 2" spool
Bondhead	Ball-Wedge for gold wire Standard capillaries 16mm length, (opt. 19 mm)
Ultrasonic System	F&S Generator 67 kHz (optional 120, 130, 140kHz)

Bonder Base

Axes

- Working area X/Y-axis 100 x 100 mm
- Step resolution 1 µm programmable
- Programmable Z-axis with 60mm stroke

Hardware

- Dual-Core PC with Windows OS Ethernet
- USB 2.0/3.0, LCD Color display 22"
- GigE-CMOS-Color camera
- Network compatible with program archiving

Software

- Single bonds up to complex programs,
- Loop shapes can be saved in libraries
- Optional pattern recognition

Placement accuracy: +/- 5 µm @ 3 sigma, incl. Tool / no wire on F&S BONDTEC standard substrate

Repeatability: +/- 3 µm @ 3 sigma, incl. Tool / without wire on F&S BONDTEC standard substrate

Loop height accuracy: +/- 5 µm @ 3 sigma, for thin wire 5630 with 25 µm aluminum wire on F&S BONDTEC standard substrate

Die 56xxi Series:

The semi-automatic Gold Ball-Bonder 5610i fills the gap between the manual and semi-automatic Ball Bonder.

The 5610i is fully PC controlled and allows any number of bonds and bumps to be programmed. Pre-programmed adjust points are targeted through the camera's cross hair targeting system and the programmed bonds or bumps are executed automatically.

Two operating modes are available: Single bond for repair of various bond samples and making single bonds (manual/automatic) and multi wire for teaching and bonding chips or various bond samples (semi and fully automatic).

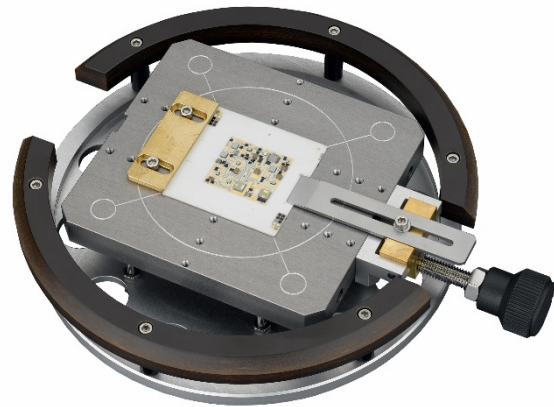
The 5610i can also be used as Thin Wire Wedge Wedge or Heavy Wire as well as pull-/shear tester by simply replacing the bond head and loading the appropriate software.

Set-up time: ~ 3 minutes.
Ask us for more information!

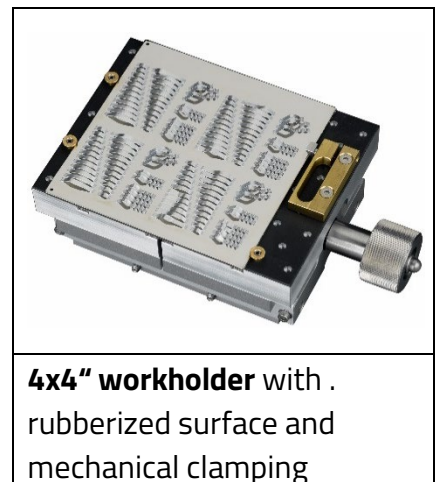
- Speed** 1 wire / 2 - 3 seconds
- Dimensions** W x D x H – 70 x 65x 70 cm, weight approx. 75 kg
- Connections** 100-240 VAC, 1 Phase, 50/60 Hz, max 500 VA
Ø 6mm standard vacuum tubing
- Heater controller** Intergrated in the machine 0-250C°

Workholder

Standard-Workholder
for parts up to 4x4"
with Vacuum und mechanical clamping



Optional:



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